HIGH TEMPERATURE POTTING AND CASTING MATERIALS

Technical Bulletin A4

Aremco offers the most expansive range of ceramic-based materials used for the assembly of high temperature, high power electrical devices as well as high temperature fixtures, molds and tooling. These materials, based on aluminum oxide, aluminum nitride, magnesium oxide, silicon dioxide, silicon carbide, zirconium oxide, and zirconium silicate, offer unique properties with respect to operating temperature, thermal conductivity, dielectric and mechanical strength.

Ceramacast™ products are supplied in either one- or two-part systems. One-part systems are typically mixed with water or a specialty binder system that is used to improve moisture resistance. Materials set at room temperature in several hours, then cure at ~250 °F in 2-4 hours to provide optimal electrial and mechanical properties. Twopart systems have varying set times and are similiarly cured at 250 °F in 1-2 hours.



Ceramacast™ 575N pots halogen lamp.



Ceramacast™ 576N pots high power resistor.

TYPICAL APPLICATIONS

Electrical

- · Ballast Resistors
- Cartridge Heaters
- · Case Resistors
- · Ceramic Fiber Heaters
- Electrical Feed-Thrus
- · Gas Ignitors
- Halogen Lamps
- · High Temp Air Filters
- Infrared Heaters
- PTC Devices
- Rheostats
- Temperature Sensors

Metallurgical

- · Brazing Fixtures
- Crucibles
- · Encapsulating RF Coils
- Furnace Carriers
- Heating Element Holders
- Induction Heating Tools
- Molds for Powder Metallurgy
- · Rapid Prototype Molds
- Sintering Boats
- Standoffs
- · Welding Jigs



Ceramacast™ 584 casts fine detail welding fixture.



Ceramacast™ 646N seals heating apparatus.



Ceramacast™ 673N bonds SiC combustion nozzle



Ceramacast™ 645N insulates support collar.



Ceramacast™ 673 used to mold down hole drill bits.



Ceramacast™ 586 used to assemble silicon carbide ignitor.

SELECTION CRITERIA

- Is the application for assembly potting or to cast a part?
- What is the operating temperature?
- What is the size and geometry of the component?
- What type of materials are being assembled or molded?
- · Is low or high thermal conductivity required?
- What are the required electrical properties?
- Does the application require high mechanical strength?
- How will the material be dispensed?
- Is the material pot life a consideration?
- Is the cure schedule a consideration?

		HIGH	HIGH TEMPERATURE	RATURE	POTTING		& CASTING MATERIALS PROPERTIES	ATERIAL	S PROP	ERTIES			
Product Number	510	2/2	N-676	N-9/2	895	N-676	584	645-N	673	N-£29	N-9 1 9	286	006
Trade Name	Ceramacast™	Ceramacast™ Ceramacast™ Ceramacast™ Ceramacast™ Ceramacast™	Ceramacast™	Ceramacast™	Ceramacast™	Ceramacast™	Ceramacast™	Ceramacast™	Ceramacast TM Ceramacast TM	Ceramacast™	Ceramacast™	Ceramacast™	Ceramacast™
Major Constituent		*	Aluminun Oxide			Aluminum Nitride	Magnesium Oxide	Silicon Dioxide	Silicon Carbide	Carbide	Zirconium Oxide	Zirconium Silicate	Silicate
Description	Coarse Grain Castable for Producing Large High- Temp Tooling	Fine Grain Potting Compound for Small Devices	Fine Grain Castable for High Temp Potting and Tooling	Medium Grain Castable for Large High- Temp Potting and Tooling	Fine Grain Castable for High-Temp Tooling, Good Surface Finish	Fine Grain, Thermally Conductive Potting Compound	Two-Part, Ultra Quick-Set Casting and Potting	Low Thermal Conductivity, Low Expansion Potting Compound	Two-Part Molding Compound, Good Thermal Conductivity	Adhesive and Potting Compound for Graphite and SiC Components	High Density, High Strength Castable and Potting Compound	High Strength, Dispensable Adhesive and Potting Compound	High Density, High Strength Molding Compound
Temperature Limit, °F (°C)	3200 (1760)	3000 (1650)	3000 (1650)	3000 (1650)	2500 (1371)	2200 (1200)	2800 (1535)	3000 (1650)	2500 (1371)	2500 (1371)	3000 (1650)	2800 (1535)	2800 (1535)
CTE, in/in/°F (°C)	3.9 (7.0)	4.3 (7.7)	4.3 (7.7)	4.1 (7.4)	4.0 (7.2)	2.9 (5.2)	6.5 (11.7)	1.5 (2.7)	3.8 (6.8)	2.9 (5.2)	3.1 (5.6)	2.7 (4.9)	2.8 (4.0)
Volume Resistivity, ohm-cm @ RT	109	109	109	109	N/A	1013	109	109	N/A	N/A	109	109	109
Dielectric Strength, volts/mil @ RT	75	150	150	150	N/A	300	100	300	N/A	N/A	250	125	125
Compressive Strength, psi	8,000	7,500	11,800	10,200	8,200	2,000	4,500	7,000	5,000	5,000	11,500	8,000	8,000
Porosity, %	< 7.0	< 6.0	< 2.0	< 2.0	< 6.0	< 3.0	< 6.0	< 5.0	< 9.0	< 4.0	< 2.0	< 2.0	< 5.0
Hd	3-4	3-4	2-3	2-3	9-9	2-3	11-12	2-3	9-9	2-3	2-3	2-3	9-9
Moisture Resistance	Excellent	Excellent	Excellent	Excellent	Excellent	Good	Excellent	Excellent	Excellent	Excellent	Excellent	Excellent	Excellent
Alkali Resistance	Good	Good	Good	роод	рооб	Good	Good	Good	Good	Good	Good	Good	Good
Acid Resistance ①	Good	Good	Good	рооб	Good	Good	Good	Good	Good	Good	Good	Good	Good
No. Components	1 + H ₂ 0	1 + H ₂ 0	1 + H ₂ 0 ©	1 + H ₂ 0 ©	2	1 + H ₂ 0 @	2	1 + H ₂ 0 ②	2	1 + H ₂ 0 ©	1 + H ₂ 0 ©	1 + H ₂ 0 ②	2
Mix Ratio, powder:liquid	100 : 15-19	100:19-22	100 : 13-15	100 : 12-14	100 : 15-17	100 : 16-18	100:25-30	100 : 18-20	100:17-20	100 : 9-11	100 : 14-17	100 : 14-16	100 : 15-17
Mixed Viscosity, cP	12,000	16,000	11,000	9,000	22,000	15,000	18,000	10,000	16,000	12,000	000'6	15,000	25,000
Shrinkage, % at 1000 °F	< 1.0	< 1.0	< 0.3	< 0.3	< 1.0	< 0.3	< 4.0	< 0.3	< 1.0	< 0.3	> 0.3	< 0.3	< 1.0
Pot Life, hrs	2-3	2-3	1-2	1-2	1	1-2	< 10 mins	1-2	< 20 mins	1-2	1-2	1-2	< 20 mins
Shelf Life, months	12	12	12	12	12	12	12	12	12	12	12	12	12
Color	Light Gray	White	White	White	White	Light Gray	Off-White	Off-White	Gray	Gray	Tan	Off-White	Off-White
Approximate Powder Density, Ibs/gal	15	12	12.5	14.5	12	10.5	12	11	12	14.5	15.5	14	13

All products are attacked by hydrofluoric acid.
 These products can be mixed alternatively with HLB-1 Hydrophobic Liquid Binder to achieve higher moisture resistance

APPLICATION PROCEDURES

Mixing

Blend powder thoroughly prior to adding water or liquid binder. Use the following mix ratios adding the water or liquid binder into the powder and mixing thoroughly until smooth and uniform. Pour the mixture carefully from one side of the part. Vibrate and/or degas as required to help eliminate air bubbles. Agitate continuously or refrigerate to extend the pot life.

	Major		Weight Rati	os	
Product	Constituent	Powder	Liquid	Min	Max
510	Aluminum Oxide	100	Water	15	19
575	Aluminum Oxide	100	Water	19	22
575-N	Aluminum Oxide	100	Water, HLB-1	13	15
576-N	Aluminum Oxide	100	Water, HLB-1	12	14
895	Aluminum Oxide	100	LB-1	15	17
675-N	Aluminum Nitride	100	Water, HLB-1	16	18
584	Magnesium Oxide	100	584-L	25	30
645-N	Silicon Dioxide	100	Water, HLB-1	18	20
673	Silicon Carbide	100	LB-1	17	20
673-N	Silicon Carbide	100	Water, HLB-1	9	11
646-N	Zirconium Oxide	100	Water, HLB-1	14	17
586	Zirconium Silicate	100	Water, HLB-1	13	15
900	Zirconium Silicate	100	LB-1	15	17

Curing

Ceramacast[™] 510, 575, 673, 895, 900

- Cover part with a plastic sheet or locate in a humidity chamber for 16-24 hours.
- 2) Bake at 200 F for 3 hours.
- 3) Final cure at 250 F for 3 hours.

Ceramacast™ 584

- Material will set in less than 10 minutes. Extend pot life by chilling the liquid to ~50 F.
- 2) Air dry for a minimum of 2 hours.
- 3) Bake at 200 for 2 hours.
- 4) Final cure at 250 for 3 hours.

Ceramacast[™] 575-N, 576-N, 586, 645-N, 646-N, 673-N, 675-N

- 1) Air dry for a minimum of 8 hours.
- 2) Bake at 200 F for 2-4 hours.
- 3) Final cure at 250 F for 3 hours.
- Final cure at 450 F for 30-60 minutes when using the HLB-1 Hydrophobic Liquid Binder.

Special Notes

- 1) Chemically absorbed water will remain in all products even after final curing at 250 °F. Based on thermogravimetric studies, it is expected that 100% of chemically absorbed water will be driven off in the 800-1000 °F range. Curing at higher temperatures should be performed to obtain optimal electrical resistance and mechanical strength.
- Possible causes of cracking include (i) excessive water or liquid binder, (ii) curing is too rapid, or (iii) cross-sectional thickness is too high. Contact Aremco for assistance if cracking persists.
- Ceramacast[™] products tend to react with aluminum molds. Use EZ-Cast[™] 580-N Flexible Silicone Rubber Molding Compound to avoid problems when casting ceramic parts.

Safety Precautions

- Refer to Material Safety Data Sheets before using Aremco's Ceramacast™ or EZ-Cast™ compounds.
- 2) For Ceramacast™ products, avoid prolonged skin contact to prevent irritation. Wear a dust mask and work in a well-venilated area. If any material enters the eyes, flush with plenty of water and consult a physician.
- 3) EZ-Cast™ should be handled in a well-ventilated area wearing rubber gloves. Any spillage can be cleaned up using isopropyl alcohol. If any material gets onto the skin, wash with isopropyl alcohol or other solvent, followed by a soap and water rinse. If there is eye contact, flush with water for 10 minutes and consult a physician.

SILICONE MOLDING COMPOUNDS

Aremco's EZ-Cast™ 580N is an ideal compound for producing high reliability master molds. This silicone rubber compound exhibits high tear strength, very low shrinkage and high flexibility, all requirements for detailed reproduction.

	PROPE	RTIES		
Te	emp. Limit, °F (°C)	392 (200)		
FI	exibility	High		
Ha	ardness, Durometer, Shore A	40		
Te	ensile Strength, psi	700 Min		
Te	ear Strength, Die B lb/in	110 Min		
EI	ongation, %	350 Min		
_	No. of Components	2		
i i	Mixed Viscosity, cps	60,000		
Mixed Viscosity, cps Specific Gravity, gms/cc Mix Ratio, resin:catalyst		1.5		
Mix Ratio, resin:catalyst		10:1		
Pot Life, mins		30		
Shelf Life, @RT, months		6		
Color		White resin, Maroon catalyst		
Weight/Gal		10 lbs resin, 1 lb catalyst		

Instructions For Use

- Machine a master pattern from aluminum and secure master into an aluminum box with removable sides. If a wooden mold is used, make sure that the mold is sealed with wax and that tapers are included to facilitate removal. Mold should allow for a cast part wall thickness of 3/8" - 1/2" minimum.
- Premix base and activator thoroughly before blending the components together in a ratio of 10 parts base to 1 part activator.
- 3) Vacuum degas at 29 in Hg. The mixture will rise to about 3-4 times its original volume, then collapse. Hold vacuum for another 1-2 minutes then release.
- 4) Pour slowly into a master, to fill all details and prevent air entrapment. Cure for 16-24 hours at room temperature, or 3-4 hours at 120 °F, or 1-2 hours at 150 °F. In humid atmosphere, heat cure for best results.

EZ-CAST™ FLEXIBLE MOLDS IN TWO EASY STEPS



Place the machined master, a duplicate of the finished casting, into a pan, and pour the EZ-Cast $^{\text{TM}}$ over the master.



Cure the EZ-Cast™ mold and peel out your finished pliable mold.

SIL-BOND™ 905 SILICONE-CERAMIC POTTING COMPOUND

Sil-BondTM 905 is a silicone-bonded, ceramic-filled, high temperature adhesive and potting compound for use in a wide range of applications to 900 °F (482 °C). This material is ideal for use in potting applications such as high power case resistors and cartridge heaters where excellent dielectric strength and moisture protection are required.

PROPERTIES - 9	SIL-BOND™ 905
Major Constituent	Fused Silica - Silicone
Temp. Limit, °F (°C)	900 (482)
Dielectric Strength, volts/mil	>250
Moisture Resistance	Excellent
Porosity After 900 °F, %	<1.0%
Shrinkage, % at 900 °F	<1.0%
Color	White
No. of Components	2
Mix Ratio, powder:liquid	2.4:1
Mixed Viscosity, cP	Paste
Recommended Cure	16-24 Hours @ Room Temp.
	+ 30 Minutes @ 150 °F
	+ 30 Minutes @ 200 °F
	+ 30 Minutes @ 250 °F
	+ 30 Minutes @ 300 °F
	+ 30 Minutes @ 450 °F